REMARKS

I. STATUS OF THE CLAIMS

Claims 1-3, 5-8, 10-13 and 15-19 are currently pending.

The claims are amended to change the phrase "organic dielectric layer" to "organic polymer dielectric layer". Support for the amendments is found, for example, on page 3, line 18, to page 4, line 4; and page 7, lines 24-25, of the specification.

Claim 8 is amended to recite that "the protective layer has a porous body of a thickness ...". Support for the amendment is found, for example, on page 10, lines 9-15, of the specification.

Claim 11 is amended to recite "an organic compound layer containing MG formed on the inorganic dielectric layer and for forming a protective layer", and to change "protective layer" to "organic compound layer". Support for the amendments is found, for example, on page 10, lines 10-19, of the specification.

II. REJECTION OF CLAIM 1-3, 5-7, 10-13, 15-17 AND 19 UNDER 35 USC 102(B) AS BEING ANTICIPATED BY BUSIO (US 2001/0005115 A1)

Claim 1 recites, in part, a dielectric layer and a protective layer of MgO being formed in this order on a substrate. Claim 1 also recites that the dielectric layer is a laminate of an organic polymer dielectric layer and an inorganic dielectric layer in this order from a side of the substrate, the inorganic dielectric layer thereby being between the protective layer and the organic polymer dielectric layer.

Please note that claim 1 is amended to recite an organic *polymer* dielectric layer. Support for the amendment is found, for example, on page 3, line 18, to page 4, line 4; and page 7, lines 24-25, of the specification.

Various embodiments of the present invention, with the inorganic dielectric layer between the protective layer and the organic polymer dielectric layer, have an effect of preventing the organic dielectric layer from being deteriorated and being peeled off. See, for example, page 20, lines 17-21, of the specification.

Busio discloses a plasma display panel comprising electrodes 2 and 4 formed on a front substrate 1; a dielectric layer 5 covering the electrodes 3 and 4; and an absorbing layer 33 formed on the dielectric layer 5 (FIG. 1B). In paragraphs [0024]-[0030] of Busio, it is described that the dielectric layer 5 is formed by a sol-gel method and that the raw material for the dielectric layer 5 contains colloidal silica and a silance compound as its main components.

More specifically, in Busio, the dielectric layer 5 is formed by heating a layer of the raw

material for the dielectric layer 5 in inert gas atmosphere at 500 to 550 °C. By heating the raw material layer at such high temperatures, the organic components contained in the raw material layer for the dielectric layer 5 are removed, and thus the dielectric layer 5 is obtained as an inorganic layer. The assumption that the dielectric layer 5 is an inorganic layer is supported by the specification of Busio. For example, paragraph [0009] and claim 4 of Busio state that the dielectric layer 5 is made of silicon oxide.

Accordingly, the dielectric layer 5 of Busio is completely different from the organic polymer dielectric layer recited, for example, in claim 1.

Although the above comments are specifically directed to claim 1, it is respectfully submitted that the comments would be helpful in understanding various differences of various other claims over the cited reference.

In view of the above, it is respectfully submitted that the rejection is overcome.

III. REJECTION OF CLAIMS 1-3, 5-8, 10-13 AND 15-19 UNDER 35 USC 103 AS BEING UNPATENTABLE OVER AOKI (US 2003/0038599) IN VIEW OF BUSIO

The above comments for distinguishing over Busio also apply here, where appropriate.

Aoki does not describe that two dielectric layers are used. In other words, in Aoki, there is no motivation to use two dielectric layers. Thus, there is no reason to combine two dielectric layers of Busio with Aoki.

In view of the above, it is respectfully submitted that the rejection is overcome.

IV. IDS

An IDS was filed on March 16, 2006.

It is respectfully requested that the Examiner acknowledge the IDS.

V. CONCLUSION

In view of the above, it is respectfully submitted that the application is in condition for allowance, and a Notice of Allowance is earnestly solicited.

If any further fees are required in connection with the filing of this response, please charge such fees to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

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By: _____
Paul I. Kravetz
Registration No. 35,230

1201 New York Avenue, NW, Suite 700
Washington, D.C. 20005
Telephone: (202) 434-1500
Facsimile: (202) 434-1501